

SPARKLE Intel® Arc™ Pro Series Graphics Card Solutions



Intel® Arc™ Pro Series Graphics Card



High-Capacity Memory for Larger AI Models

Up to 32 GB memory lets you run larger AI models and complex datasets.

Linux Support for Multi-GPU AI

Combine the power and memory of multiple GPUs to execute AI models in Linux that take 100+ GB of VRAM.

Certifications for Reliable, Trusted Performance

Built on decades of software collaboration, Intel® works closely with leading Independent Software Vendors (ISVs) to certify Intel® Arc™ Pro graphics hardware and drivers for professional applications.

Single Root IO Virtualization (SR-IOV)

Intel® Arc™ Pro B series Graphics Card supports SR-IOV technology, and each card can support up to 7 virtual functions (VFs).

Intel® Arc™ Pro Series Overview

SKUs	Xe Cores	GDDR6	TOPS (Int8)	PCIe Configuration	TBP (Up To)	Graphics Output
Intel Arc Pro B70	32	32 GB	367	PCIe 5.0 x16	330W	4x DP 2.1
Intel Arc Pro B65	20	32 GB	197	PCIe 5.0 x16	240W	4x DP 2.1
Intel Arc Pro B60	20	24 GB	197	PCIe 5.0 x8	200W	4x DP 2.1
Intel Arc Pro B50	16	16 GB	170	PCIe 5.0 x8	75W	4x DP 2.1

SPARKLE Intel® Arc™ Pro B70 Series



Blower

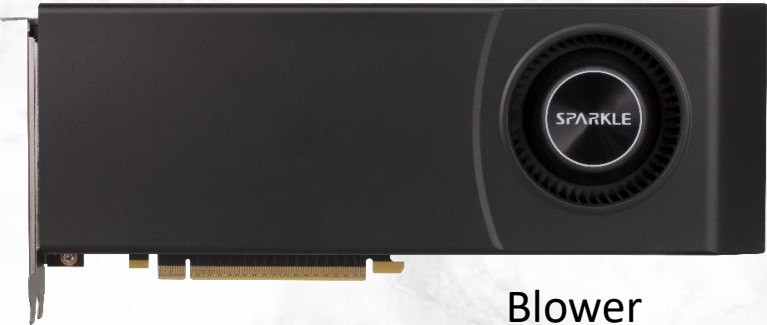


Passive



Model	Graphics Clock (Up To)	TOPS (INT8)	GDDR6	TBP	SR-IOV (Up To)	DIMENSION
Blower	2800MHz	367	32 GB	330W	7 VFs	289 x 112 x 40mm
Passive	2800MHz	367	32 GB	275W	7 VFs	289 x 112 x 40mm

SPARKLE Intel® Arc™ Pro B65 Series



Blower

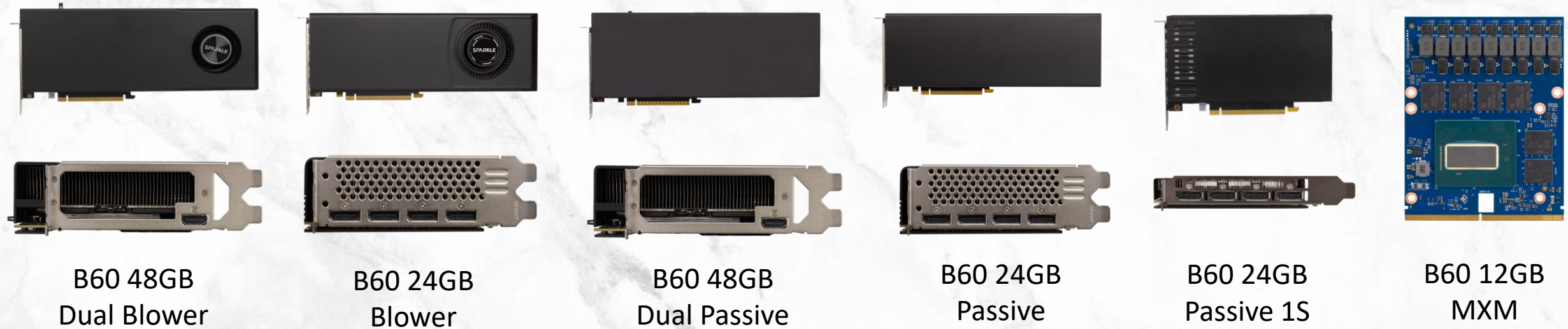


Passive



Model	Graphics Clock (Up To)	TOPS (INT8)	GDDR6	TBP	SR-IOV (Up To)	DIMENSION
Blower	2400MHz	197	32 GB	240W	7 VFs	289 x 112 x 40mm
Passive	2400MHz	197	32 GB	200W	7 VFs	289 x 112 x 40mm

SPARKLE Intel® Arc™ Pro B60 Series



Model	Graphics Clock (Up To)	TOPS (INT8)	GDDR6	TBP	SR-IOV (Up To)	Form Factor	DIMENSION
Dual Blower	2400 + 2400MHz	197 + 197	24 + 24 GB	440W	-	Dual Slot	300 x 130 x 40mm
Dual Passive	2400 + 2400MHz	197 + 197	24 + 24 GB	400W	-	Dual Slot	300 x 130 x 40mm
Blower	2400MHz	197	24 GB	200W	7 VFs	Dual Slot	289 x 112 x 40mm
Passive	2400MHz	197	32 GB	200W	7 VFs	Dual Slot	289 x 112 x 40mm
Passive 1S	2000MHz	197	24 GB	120W	7 VFs	Single Slot	182 x 112 x 21mm
MXM	1500MHz	197	12 GB	90W	-	MXM Type-B	82 x 105mm

SPARKLE Intel® Arc™ Pro B50 Series



B50 16GB Blower



B50 16GB Blower
Low Profile



B50 16GB Passive 1S
Low Profile

Model	Graphics Clock (Up To)	TOPS (INT8)	GDDR6	TBP	SR-IOV (Up To)	FORM FACTOR	DIMENSION
Blower	2600MHz	170	16 GB	72W	7 VFs	Single Slot	242 x 112 x 21mm
Blower	2600MHz	170	16 GB	72W	7 VFs	Dual Slot, Low Profile	168 x 69 x 20mm
Passive 1S	2600MHz	170	16 GB	72W	7 VFs	Single Slot, Low Profile	168 x 69 x 20mm

NEXT-GEN AI INFRASTRUCTURE

SPARKLE Intel® Arc™ Pro Solutions

Scaling Enterprise AI from Workstation to Data Center
with 768GB VRAM Power.

| AI Use Case: From Dev to Deployment



Vibe Coding

16x Intel Arc Pro GPUs run Qwen3-Coder-Next with 260K context window at 7.5+ TPS.



Edge Agents

Single Intel Arc Pro workstation supports 64 concurrent requests for a 150-agent support team.



LLM Fine-Tuning

Up to 768GB VRAM enables on-premise fine-tuning of multimodal Large Language Models.

LLM Model Compatibility

LLM Model	High-Capacity (Server)	Efficiency (Workstation)
DeepSeek	R1-671B / V3-685B	R1-Distill-70B
Meta / Mistral	Llama 3.1-405B / Mixtral-8x22B	Ministral-8B / Mixtral-8x7B
Qwen / Alibaba	3-235B (A22B) / VL-30B	Coder-Next 3.5-35B
Microsoft / GPT	GPT-OSS-120B	GPT-OSS-20B

Infrastructure Deep Dive

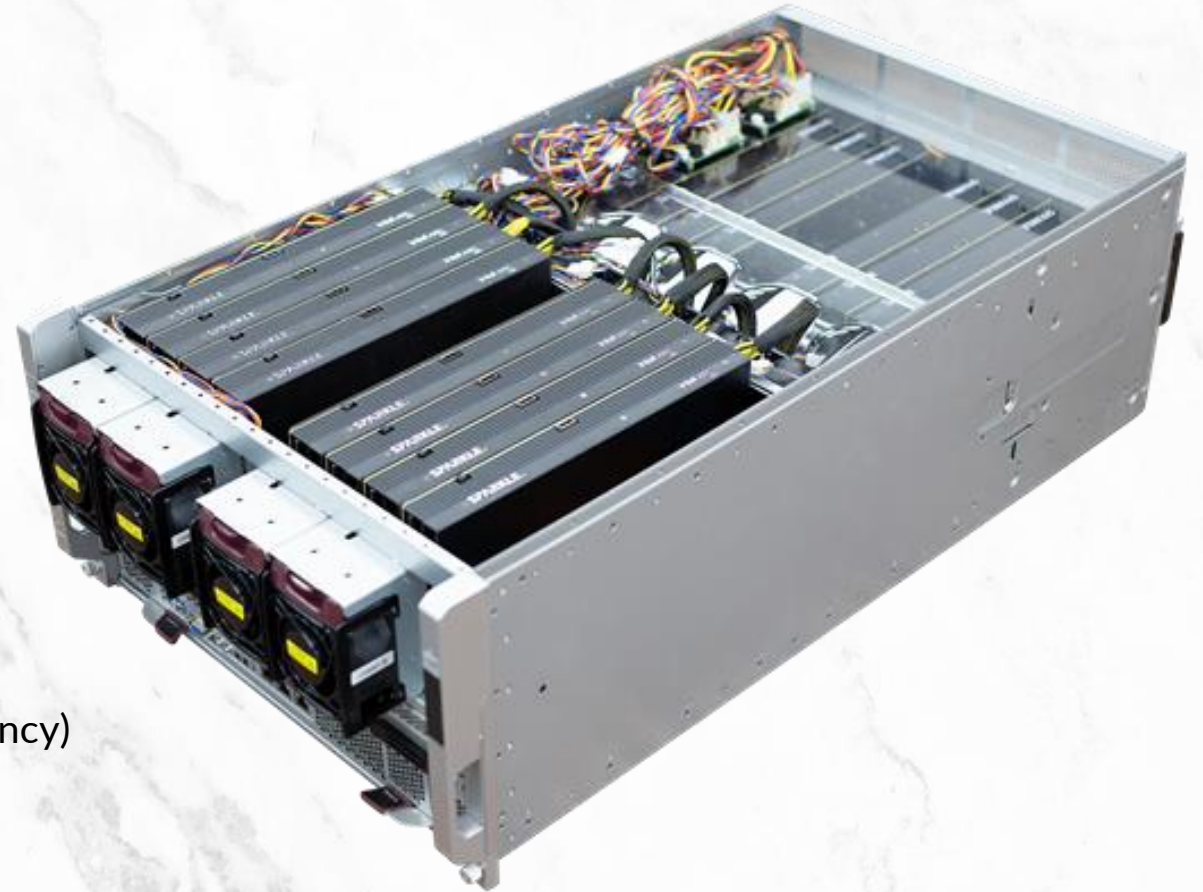
Datacenter Precision.
Workstation Flexibility.

| C741-6U-16P: The VRAM Powerhouse

768GB VRAM Cluster

Ultimate high-density configuration supporting 16x Sparkle Intel® Arc™ Pro B60 48GB Dual Graphics Cards in a 6U chassis.

- ✓ 16x Dual-Slot spaces
- ✓ 16x PCIe 5.0 x16 interfaces
- ✓ 2x 4th or 5th Intel® Xeon® Processor
- ✓ 5x 2,700W 80+ Titanium Grade Power Supply (4 + 1 Redundancy)



Server System Solutions



Model	C741-4U-8P		C741-6U-16P
Processors	4 th Intel® Xeon® Processor (Sapphire Rapids) or 5 th Intel® Xeon® Processor (Emerald Rapids) , Up to 64 Cores		
BMC	ASPEED AST2600: IPMI2.0		
DDR5	Memory Support: DDR5 RDIMM / 3DS RDIMM with 32 Slots 5 th Intel® Xeon® Xeon® : 5600 MT/s (1DPC), 4400 MT/s (2DPC) 4 th Intel® Xeon® Xeon® : 4800 MT/s (1DPC), 4400 MT/s (2DPC)		
Storage	12x Hot-swap 3.5" drive bays (10x SATA 6.0Gbps + 2x U.2 PCIe 4.0) 2x PCIe 3.0 x2 M.2 2280 / 22110 (PCH)		4x 2.5" drive bays (4x PCIe 5.0 NVMe U.2) 2x PCIe 3.0 x2 NVMe M.2 2280 / 22110 (PCH)
PCIe Expansion	8x PCIe 5.0 x16, Double-wide slot 1x PCIe 5.0 x16, Single-wide slot 1x PCIe 4.0 x8, Single-wide slot All slots feature direct CPU connectivity. (Switchless)		16x PCIe 5.0 x16, Double-wide slot (Switch) 2x PCIe 5.0 x16, Double-wide slot (CPU Direct)
Up to VRAM	384GB, 8x Intel Arc Pro B60 Dual 48GB		768GB, 16x Intel Arc Pro B60 Dual 48GB
	256GB, 8x Intel Arc Pro B70 32GB		512GB, 16x Intel Arc Pro B70 32GB
Power Supply	4x 2,700W 80+ Titanium Grade (3 + 1 Redundancy)		5x 2,700W 80+ Titanium Grade (4 + 1 Redundancy)

C741-6U-16P with 16 x Intel® Arc™ Pro B60 48GB DUAL. 768 GB VRAM

Processor	» 2x 4th Intel® Xeon® Processor or 5th Intel® Xeon® Processor
DDR5	» 8TB (Max) with 32x DIMMs Slots, RDIMM or 3DS RDIMM 5th Intel® Xeon® : 5,600 MT/s (1DPC), 4,400 MT/s (2DPC) 4th Intel® Xeon® : 4,800 MT/s (1DPC), 4,400 MT/s (2DPC)
Storage	» 4x 2.5" drive bays (PCIe 5.0 x4 NVMe U.2) » 2x PCIe 3.0 x2 NVMe M.2 2280 / 22110 (PCH)
System Firmware	» BMC ASPEED AST2600: IPMI2.0 with iKVM and vMedia support » BIOS AMI UEFI BIOS; 512Mb SPI Flash ROM
Dimensions	44.86 x 26.49 x 81.58 cm (Width x Height x Depth)
Fans	19x 8038 Fans
Expansion Slot	» 16x PCIe 5.0 x16 slots, Support FHFL double-wide GPU cards » 2x PCIe 5.0 x16 slots (CPU) , Support High speed NIC
Networking	» 2x RJ45 (1GbE) by Intel® i350 » 1x RJ45 Dedicated IPMI LAN port by Realtek RTL8211F
Power Supply	5x 2,700W 80+ Titanium Grade (4 + 1 Redundancy)

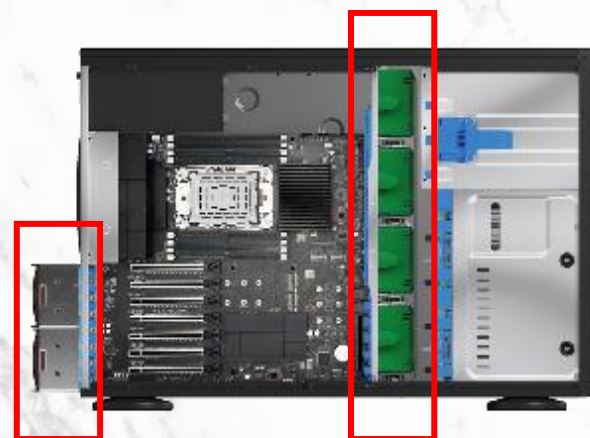


| AI Workstation System Solution

Model	CPU Platform	DDR5 (Max)	VRAM Configuration (Max)
W790-WS	Intel® Xeon® W-3500 / W-2500	2TB	192GB, 4x Intel Arc Pro B60 48GB Dual
W890-WS	Intel® Xeon® 6 Processors	4TB	128GB, 4x Intel Arc Pro B70 32GB

Convertible tower-to-rackmount with high-airflow design.

Tower workstation convertible to rackmount.



High-Airflow Chassis Design

AI Workstation System Solution

Model	W790-WS-4P	W890-WS-4P
CPU	Intel® Xeon® W-2500 or W-3500 processors, Up to 60 cores	Intel® Xeon® 6 Processors, Up to 86 cores
DDR5	2TB (Max) with 8 DIMMs, 8 Channels RDIMM: Up to 4,800 MT/s	4TB (Max) with 8 DIMMs, 8 Channels RDIMM: Up to 6,400 MT/s MRDIMM: Up to 8,000 MT/s
Chipset	Intel® W790	Intel® W890
Storage	8x Drive bays 3.5"x8 (x8 2.5" U.2 by PCIe5.0 x16 to NVMe Expansion Card)	8x Drive bays 3.5"x8 (x4 2.5" U.2 by –PCIe Gen 5.0 x16 -2 x MCIO 8i)
BMC	ASPEED AST2600: IPMI2.0	
PCIe Expansions	6x PCIe5.0 x16 (x16 Signal) slot 1x PCIe5.0 x16 (x8 Signal) slot up to 112 lanes of CPU-attached Gen5.0	6x PCIe5.0 x16 slots up to 128 lanes of CPU-attached Gen 5.0
MCIO	N/A	PCIe Gen 5.0 x16 -2 x MCIO 8i , require Intel® Xeon® 690/670/650 processors
VRAM	Option 1: 192GB, 4x Intel Arc Pro B60 48GB Dual	
	Option 2: 128GB, 4x Intel Arc Pro B70 32GB	
Power Supply	2,500W or 3,000W 80+ Platinum Grade	